This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (canceled)

2. (previously amended) The RFID tag of claim 28 wherein a pattern of the first and second contact pads is selected from a group comprising butterfly, propeller, polygon and bow-tie patterns.

3. (previously amended) The RFID of claim 28 wherein a conductive adhesive is applied to at least a portion of the first and second contact pads.

4-12 (canceled)

13-27 (previously withdrawn)

28. (currently amended) A radio frequency identification tag comprising:

a first substrate;

~~an~~ a first antenna element and a second antenna element disposed on the first substrate, wherein the first antenna element is electrically isolated from the second antenna element;

a second substrate;

a first contact pad and a second contact pad disposed on the second substrate wherein the first contact pad is electrically isolated from the second contact pad; and

a circuit coupled to the first and second contact pads,

wherein the first and second contact pads are designed to make electrical contact with the first and second antenna elements.

29. (previously added) The RFID tag of claim 28 wherein at least one of antenna element, first contact pad and second contact pad is printed.

30. (previously added) The RFID tag of claim 28 wherein the circuit is electrically coupled to the first and second contact pads.

31. (currently amended) A radio frequency identification tag comprising:

a first substrate;

an antenna element disposed on the first substrate;

a second substrate;

a first contact pad and a second contact pad disposed on the second substrate; and

a circuit coupled to the first and second contact pads,

wherein the first and second contact pads are designed to make electrical contact with the antenna element, and ~~The RFID tag of claim 30~~ wherein the circuit is electrically coupled to the first and second contact pads via a pressure sensitive adhesive film.

32. (previously added) The RFID tag of claim 28 wherein the first contact pad is disposed on the second substrate diagonally from the second contact pad.

33. (previously added) The RFID tag of claim 28 wherein the first and second contact pads are electrically isolated from each other.

34. (previously added) The RFID tag of claim 28 wherein the first and second contact pads are physically separated from each other.

35. (previously added) The RFID tag of claim 28 wherein at least one of the first and second contact pads is printed with a material selected from a group consisting of: carbon and a metalized material.

36. (previously added) The RFID tag of claim 28 wherein the antenna element is divided into a first half and a second half, and wherein the first contact pad is designed to make electrical contact with the first half of the antenna, and the second contact pad is designed to make electrical contact with the second half of the antenna.

37. (currently amended) An assembly comprising:

a first substrate having disposed thereon a first contact pad and a second contact pad, wherein the first and second contact pads are designed to couple to a first antenna element and a second antenna element; and

a second substrate overlaying the first substrate, ~~wherein~~ the second substrate ~~comprises~~ comprising an aperture,

wherein the aperture exposes at least a portion of the first contact pad and at least a portion of the second contact pad, and wherein the aperture is patterned such that it facilitates a placement of a circuit ~~in order~~ that couples ~~to couple~~ to the first and second contact pads, and wherein the second substrate is designed to be removed from the first substrate prior to coupling the first and second contact pads to the first and second antenna elements, and wherein the first and second antenna elements are separate from the assembly.

38. (previously added) The assembly of claim 37 wherein the second substrate adheres to the first substrate via an adhesive~~, and wherein the first substrate can be removed from the second substrate~~.